



Material Content Data Sheet



Sales Product Name	ESD18VU1B-02LS E6327			Issued		29. August 2013		
MA#	MA000919304							
Package	PG-TSSLP-2-1			Weight*		0.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.44		4409	
	noble metal	gold	7440-57-5	0.003	1.71		17113	
	inorganic material	silicon	7440-21-3	0.020	12.68	14.83	126797	148319
leadframe	non noble metal	nickel	7440-02-0	0.036	23.01	23.01	230068	230068
wire	noble metal	gold	7440-57-5	0.002	1.50	1.50	14974	14974
encapsulation	organic material	carbon black	1333-86-4	0.001	0.49		4865	
	plastics	epoxy resin	-	0.010	6.57		65679	
	inorganic material	silicondioxide	60676-86-0	0.066	41.59	48.65	415978	486522
leadfinish	noble metal	gold	7440-57-5	0.004	2.60	2.60	26020	26020
plating	noble metal	silver	7440-22-4	0.015	9.41	9.41	94097	94097
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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